LCCC - Issue #3 (Winter 2026)

Welcome to the Winter issue of the LCCC Newsletter!

As we enter a new year, the **Latvian Chip Competence Centre (LCCC)** continues its work to strengthen Latvia's position within the European semiconductor ecosystem. Recent months have marked important progress – ranging from deeper regional **collaboration with Baltic and Nordic partners** to **active participation in Europe-wide coordination activities** and **strategic engagement with Latvian industry**.

In this edition, we highlight key developments from the end of 2025, including major international meetings, industry workshops, and cooperation initiatives that shape **LCCC's strategic direction for 2026**. You will also find an overview of **upcoming events and opportunities** within the semiconductor and microelectronics community across Europe.

Thank you for following our work as we continue building a strong, connected, and innovation-driven microchip ecosystem for Latvia and the wider region.

Recent events

Baltic – Nordic Chip Competence Centres Sign Memorandum in Lund

On 9 December 2025, representatives of the Latvian Chip Competence Centre participated in the **first joint meeting of the Baltic and Nordic Chip Competence Centres**, hosted by the Swedish Chips Competence Centre in Lund, Sweden. The event

brought together more than 40 participants and marked a significant step toward deeper regional collaboration in support of the *Chips for Europe* initiative.

During the meeting, a **Memorandum of Understanding was signed between all four Nordic centres** (Finland, Sweden, Norway, Denmark) and the three Baltic States – Latvia, Lithuania, and Estonia. This agreement builds on the momentum created during the Techritory Forum held in Riga in October and sets the foundation for long-term cooperation in semiconductor innovation, research, and capacity building.

Beyond the formal signing, **partners agreed on concrete next steps** to ensure practical impact:

- Quarterly coordination meetings involving all seven competence centres
- Monthly virtual meetings of four thematic focus groups: Operations & Best Practices, Outreach & Events, Training, and Technology Offers

During the meeting discussions have already begun on **key challenges** faced by SMEs in chip development, including access to PDKs, pilot lines, and IP management. Encouragingly, several centres shared positive examples of how targeted support has enabled SMEs to progress toward their first tape-outs.

Participants also highlighted the **importance of a coordinated regional service portfolio**. Since industry needs vary widely, no single centre can address all challenges alone; therefore, Baltic–Nordic cooperation will enable each centre to leverage the strengths of the wider network and offer more tailored support to companies working on chip design and development.

LCCC Industry Workshop: Aligning Priorities for 2026 and Beyond

The Latvian Chip Competence Centre wrapped up 2025 by **bringing industry and academia together to discuss strategic development priorities for 2026** and the next 3–5 years. The LCCC Industry Workshop gathered **leaders and experts from key companies shaping Latvia's technology landscape**, including LMT, Bosch, SAF Tehnika, MikroTik, Frankenburg Technologies, HansaMatrix, and NEWT21.

The aim of the workshop was to **collect strategic insights from industry partners** and evaluate LCCC's current and planned activities, **ensuring strong alignment with real market needs**. Discussions focused on several priority themes:

- industry-driven and practice-oriented education,
- thematic verticals for future development,
- skills and talent requirements,
- the role of the Competence Centre as a platform for experimentation, learning, and collaboration.

Participants provided valuable feedback that will contribute directly to the refinement of LCCC's strategic roadmap. As a result of the workshop, concrete next steps and action points were identified, offering a clear direction for activity planning in 2026.

The event also reaffirmed strong support from leading Latvian technology companies, highlighting a shared commitment to strengthening the national semiconductor ecosystem and advancing Latvia's role in the broader European microchip landscape.

LCCC Joins the First European Network of Chips Competence Centres Annual Meeting in Brussels

The meeting opened with an **overview of the network's key performance indicators and a comprehensive assessment of the Competence Centres 'development** during their inaugural year. These presentations highlighted early achievements, areas requiring

additional focus, and the growing maturity of Europe's distributed semiconductor ecosystem.

A panel discussion on the first-year journey of the CCCs provided insights into national experiences, challenges, and lessons learned across the network. A shared message emerged throughout the exchanges: stronger coordination, deeper synergies, and sustained long-term collaboration are essential to strengthening Europe's semiconductor capabilities.

A significant theme of the meeting was **the critical importance of skills development.** Competence Centres across Europe are actively shaping educational programmes, training initiatives, and talent-development pathways to support the next generation of semiconductor specialists. The emphasis on creating opportunities not only for university students, but also for high-school learners and professionals seeking reskilling, reflects a growing recognition of workforce needs within the sector.

The ENCCC community also acknowledged **the growing role of Baltic–Nordic collaboration**. The regional initiative by bringing together Competence Centres from the Baltic States and the Nordic countries was highlighted as a promising model of cross-border cooperation that strengthens Europe's semiconductor value chain.

RTU to Build Advanced Microchip Testing Centre in Ķīpsala

Riga Technical University (RTU) is launching an ambitious project to establish a state-of-the-art **microchip testing centre** in Ķīpsala, Riga, expanding hands-on opportunities for students and startups in cutting-edge semiconductor research. The new facility aims to support faster data transmission and energy-efficient technologies, reinforcing Latvia's position in tech innovation.

🔗 ***Read more***

Upcoming Events

Innovation Mission: Exploring the Grenoble Semiconductor Ecosystem and the FAMES Pilot Line

🗓️ March 16–19, 2026

📍 Grenoble, France

🔗 **Registration**

This outbound innovation mission, organised by the ChipNL Competence Centre, **offers participants the opportunity to explore one of Europe's leading semiconductor and microelectronics hubs**. The programme includes participation in the Minalogic Business Meetings, on-site visits to CEA-Leti and the FAMES Pilot Line, as well as industrial company visits within the Grenoble ecosystem.

The mission targets companies, research institutions, and universities active in semiconductors, integrated photonics, and related technologies, aiming to strengthen European collaboration and market positioning.

Participation is limited and requires prior registration.

Image Sensors Europe 2026

🗓️ March 17–18, 2026

📍 London, UK

🔗 Event site

This is the 20th edition of the **leading conference for the digital imaging and sensor supply chain**. With over 250 industry representatives expected, it focuses on cutting-edge image sensor technologies, CMOS updates, SWIR, SPAD and depth sensing, and applications across automotive, consumer and scientific markets.

POEMS Semiconductor Spring School 2026

🗓️ April 6–10, 2026

📍 University of Aveiro, Portugal

🔗 **Event site**

The POEMS Semiconductor Spring School is a **week-long introductory programme designed for advanced bachelor and early master students interested in microelectronics and semiconductor technologies.** Over five days, participants will explore key POEMS domains, including chip design, advanced packaging, and emerging technologies.

The programme features lectures, demonstrations, and talks by leading researchers and industry specialists, offering insights into cutting-edge developments, industrial challenges, and global trends. With its dynamic format and interactive sessions, the school provides an excellent opportunity for students to deepen their understanding of the field, engage with peers, and connect with experts across academia and industry.

Participation is limited and requires prior registration.

SPIE Photonics Europe 2026

🗓️ April 12–16, 2026

📍 Strasbourg, France

🔗 Event site

This **major cross-disciplinary event covers photonics, optics, sensors, laser technologies, quantum and imaging systems**. It offers a strategic platform for companies and researchers in microelectronics, advanced packaging and integrated photonics to connect, showcase innovations and explore collaborations.

Design, Automation and Test in Europe Conference (DATE 2026)

🗓️ April 20–22, 2026

📍 Palazzo della Gran Guardia, Verona, Italy

🔗 **Event site**

DATE is **Europe's leading conference for electronic system design, automation, and test**, bringing together designers, researchers, tool developers, and industry specialists across the full spectrum of hardware and software design. The event covers integrated circuits, SoCs, reconfigurable hardware, embedded systems, and design automation tools, with a strong focus on both technology and system-level innovation.

Riga Chip Summit 2026

🗓️ May 13, 2026

📍 Riga, Latvia

The Riga Chip Summit 2026 is a **new international forum organised by the Latvian Microchip Competence Centre to advance collaboration across the European semiconductor ecosystem**. The event is expected to gather around 200 participants, including industry leaders, investors, academic institutions, competence centres, startups, and SMEs from the Nordic–Baltic region and across Europe.

The Summit will provide companies with a clear and practical overview of the EU semiconductor landscape and the opportunities available under Chips Joint Undertaking. The programme includes structured matchmaking sessions, a networking evening, and expert discussions on pilot project requirements, TRLs, co-funding logic, intellectual property, and pathways to commercialisation.

Riga Chip Summit 2026 aims to raise Latvia's visibility in the European semiconductor ecosystem and support the country's long-term ambition to transition from a chip consumer to a chip innovator by 2030.

Deep Tech Atelier 2026

🗓️ May 14–15, 2026

📍 Riga, Latvia

🔗 **Event site**

Deep Tech Atelier is the **Baltics 'largest deep-tech conference, bringing together scientists, entrepreneurs, investors, and industry leaders** for two days of keynotes, pitch sessions, and hands-on workshops. Organised by the Investment and Development Agency of Latvia, the event attracts more than 2000 participants from over 60 countries.

The programme traditionally focuses on knowledge-intensive sectors, featuring thematic pillars such as AI, quantum technologies, space, and defence. Multiple stages host international speakers, startup pitches, and practical sessions on technology commercialisation. Attendance is free, with prior registration required.

Venue details for 2026 will be announced.

Call for proposal

The **Chips for Europe** Initiative aims to build advanced technological capabilities and boost innovation across the European Union. Related OPEN and Coming Soon Calls can be found here.

🎙️ *Beyond Chips* Podcast by Chips Joint Undertaking

The Chips Joint Undertaking continues its official podcast – *Beyond Chips* – offering monthly insights into Europe's dynamic semiconductor ecosystem.

New episodes are released every first Wednesday of the month, featuring leading voices from industry, research, and policy. The podcast explores the strategic, technological, and economic dimensions of Europe's chips landscape.

🎧 Episodes 1–7 are already **available**, covering challenges, opportunities, and key innovations that are shaping the future of semiconductors in Europe.

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